Octopus

by

SWISS MADE

INDEOtec

PLASMA PROCESS EQUIPMENT

INDEOtec SA • Rue du Puits-Godet 12A • 2000 Neuchâtel
Switzerland • **www.indeotec.com**

www.indeotec.com

Octopus II

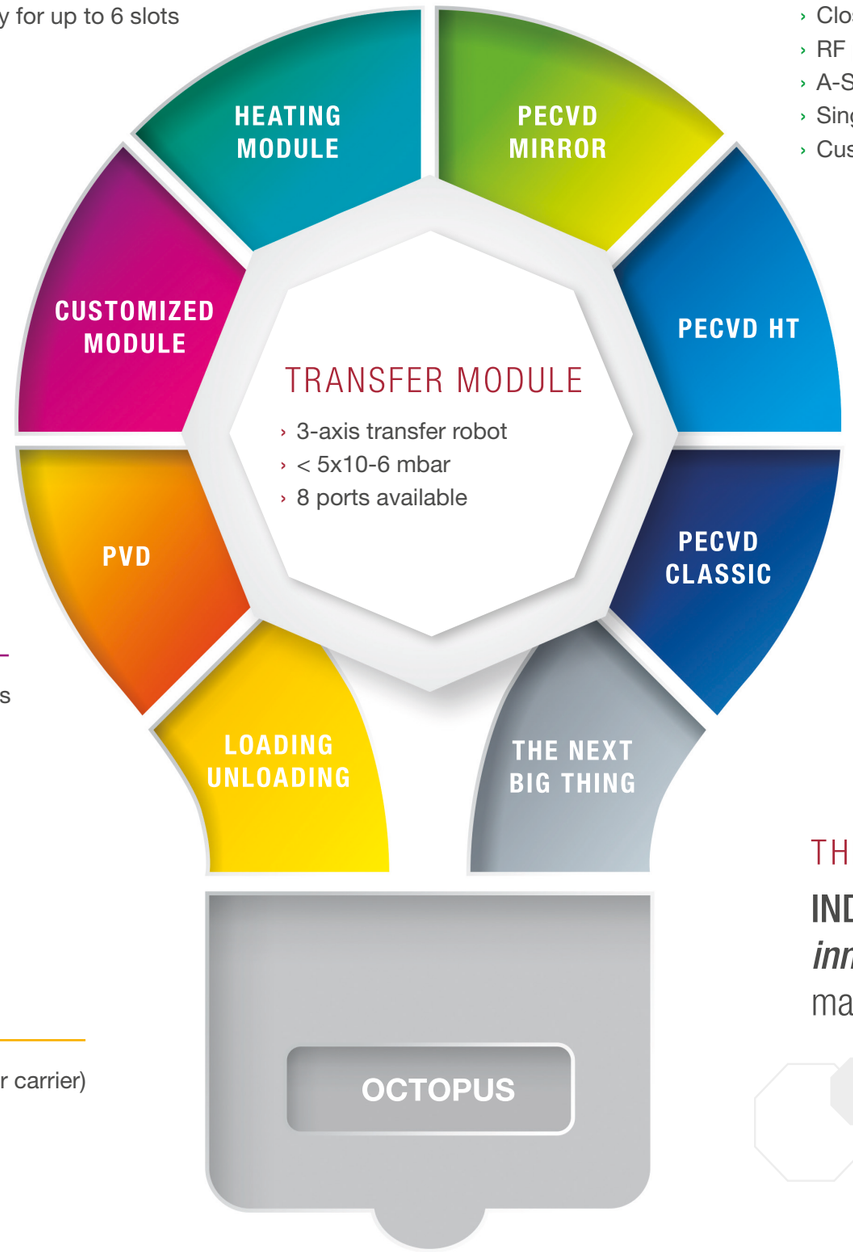
The OCTOPUS platform makes double sided deposition easy and provides consistently high film quality. Ideal for heterojunction cell development, MEMS manufacture or opto-electronic layers.

- Very flexible system concept for thin film deposition
- Excellent film thickness uniformity
- Excellent film passivation levels
- PECVD, PVD layers, or combinations in the same system
- PECVD: extremely stable plasma ignition, even at low power (<10 mW/cm^2), low bombardment
- R&D and pilot production
- Substrate size: 350 x 450 mm max. or 4 wafers per 6 inch
- Small footprint: LxWxH 2.5 x 2.5 x 1.7 meters (PECVD)
- High throughput possible: > 1.3 Mio wafers (6'') p.a.
- Fully automated system and process control
- User-friendly GUI
- Process & system data logging

SELECT YOUR PREFERRED CONFIGURATION

HEATING MODULE

- For substrate Pre-heating or Cooling
- Capacity for up to 6 slots



PECVD MIRROR

- Double-sided deposition (NO substrate flipping necessary)
- Closed reactor (enables Δp mode)
- RF plasma process (13.56 MHz) or VHF (40 MHz)
- A-Si:H thin layers (intrinsic and doped), µc-Si, mc-Si layers
- Single and multiple stack layers
- Customized thin film profiles across the entire surface

PECVD HT

- Top side deposition
- Closed reactor (enables Δp mode)
- RF plasma (13.56 MHz)
- SiNx, SiOx, SiONx …
- 450°C max. in permanent mode

PECVD CLASSIC

- Top side deposition
- Closed reactor (enables Δp mode)
- RF plasma (13.56 MHz) or VHF (40 MHz)
- a-Si:H layers (intrinsic, doped), µc-Si, mc-Si, SiGe:H layers…
- 280°C max. in permanent mode

CUSTOMIZED MODULE

- LPCVD, Hot wire, etching modules

PVD

- 3 top, 3 bottom cathode ports (planar or rotary)
- Power type: DC, pulsed DC, RF
- With separate Loading/Unloading
- Adjustable target-substrate distance
- Options: port-connected to OCTOPUS II or as Stand-alone

LOADING / UNLOADING

- 6 substrate or carrier slots (4 wafers 6" per carrier)
- Pumping/Venting station (turbo pumps)
- High-throughput per deposition cycle
- Substrate auto-tracking

THE NEXT BIG THING

INDEOtec is continuously bringing ***innovation*** to the **thin-film** manufacturing **equipment** industry.

SWISS MADE
INDEOtec
PLASMA PROCESS EQUIPMENT